



General Description

The WSD3023DN56 is the highest performance trench N-ch and P-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSD3023DN56 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

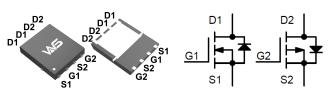
Product Summery

BVDSS	RDSON	ID
30V	14mΩ	14A
-30V	23mΩ	-12A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- CCFL Back-light Inverter

DFN5X6C-8-EP2 Pin Configuration



Absolute Maximum Ratings

		Rati		
Symbol	Parameter	N-Ch	P-Ch	Units
V _{DS}	Drain-Source Voltage	30	-30	V
V_{GS}	Gate-Source Voltage	±20	±20	V
	Continuous Drain Current, V _{GS(NP)} =10V,T _a =25 °C	14*	-12	А
I _D	Continuous Drain Current, V _{GS(NP)} =10V,T _a =70 °C	7.6	-9.7	Α
I _{DP} ^a	Pulse Drain Current Tested, V _{GS(NP)} =10V	488	-48	А
E _{AS} c	Avalanche Energy, Single pulse , L=0.5mH	20	20	mJ
l _{AS} c	Avalanche Current, Single pulse , L=0.5mH	9	-9	А
P _D	Total Power Dissipation, T _a =25 °C	5.25	5.25	W
T _{STG}	Storage Temperature Range	-55 to 175	-55 to 175	$^{\circ}$
TJ	Operating Junction Temperature Range	175	175	$^{\circ}$
R _{JA} ^b	Thermal Resistance-Junction to Ambient, Steady State	60	60	°C/W
R _{JC}	Thermal Resistance-Junction to Case, Steady State	6.25	6.25	°C/W

Note *: Max. current is limited by bonding wire.

Note a: Pulse width limited by max. junction temperature.

Note $b : R_{JA}$ steady state t=999s. $R_{\theta JA}$ is measured with the device mounted on $1in^2$, FR-4 board with 2oz. Copper. Note c : UIS tested and pulse width limited by maximum junction temperature $175^{\circ}C$ (initial temperature $T_i=25^{\circ}C$).



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V
D d	Static Drain-Source On-Resistance	V_{GS} =10V , I_D =8A		14	18.5	mΩ
$R_{DS(ON)}^{d}$		V _{GS} =4.5V , I _D =5A		17	25	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	1.3	1.8	2.3	V
I	Drain Course Leakage Current	V_{DS} =20V , V_{GS} =0V , T_J =25 $^{\circ}$ C			1	uA
I _{DSS}	Drain-Source Leakage Current	V_{DS} =20V , V_{GS} =0V , T_{J} =85 $^{\circ}$ C			30	
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, V_{DS} =0V			±100	nA
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.7	3.4	Ω
Qg ^e	Total Gate Charge	V _{DS} =15V, V _{GS} =4.5V, I _{DS} =8A		5.2		
Q _{gs} e	Gate-Source Charge			1.0		nC
Q _{gd} e	Gate-Drain Charge			2.8		
T _{d(on)} e	Turn-On Delay Time	V _{DD} =15V,R _L =15R, I _{DS} =1A,V _{GEN} =10V, R _G =6R.		6		
T _r e	Rise Time			8.6		20
T _{d(off)} e	Turn-Off Delay Time			16		ns
T _f e	Fall Time			3.6		
C _{iss} e	Input Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		545		
C _{oss} e	Output Capacitance			95		pF
C _{rss} ^e	Reverse Transfer Capacitance			55		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V , Force Current			12	Α
V_{SD}^d	Diode Forward Voltage	V_{GS} =0V , I_{S} =1A , T_{J} =25 $^{\circ}$ C			1.2	V

Note d : Pulse test ; pulse width $\!\leq\!300\mu\text{s},$ duty cycle $\!\leq\!2\%.$

Note e: Guaranteed by design, not subject to production testing.



N-Ch and P-Channel MOSFET

P-Channel Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-30			V
D d	Static Drain-Source On-Resistance	V _{GS} =-10V , I _D =-12A		23	32.5	mΩ
$R_{DS(ON)}^d$		V _{GS} =-4.5V , I _D =-5A		32	42	
V _{GS(th)}	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250uA$	-1.3	-1.8	-2.3	V
I _{DSS}	Drain-Source Leakage Current	V_{DS} =-20V , V_{GS} =0V , T_J =25 $^{\circ}$ C			-1	- uA
IDSS		V_{DS} =-20V , V_{GS} =0V , T_J =85 $^{\circ}$ C			-30	
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, V_{DS} =0V			±100	nA
Q_g^e	Total Gate Charge			13		
Q _{gs} e	Gate-Source Charge	V_{DS} =-15V , V_{GS} =-4.5V , I_{D} =-12A		1.0		nC
Q _{gd} e	Gate-Drain Charge			4.0		
T _{d(on)} e	Turn-On Delay Time			8.7		
T _r e	Rise Time	V_{DD} =-15V , V_{GS} =-10V , R_G =6 Ω ,		10		no
T _{d(off)} e	Turn-Off Delay Time	I_D =-1A , R_L =15 Ω ,		22		ns
T _f e	Fall Time	1		9.0		
C _{iss} e	Input Capacitance			580		
C _{oss} e	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		105		pF
C _{rss} e	Reverse Transfer Capacitance]		72		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V _G =V _D =0V , Force Current			-10	Α
V _{SD} e	Diode Forward Voltage	V _{GS} =0V , I _S =-1A , T _J =25℃			-1.2	V

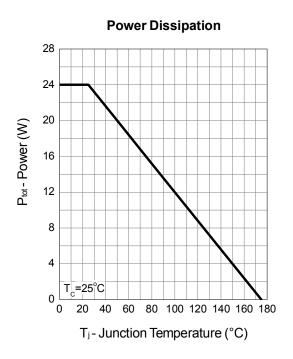
Note d : Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2%.

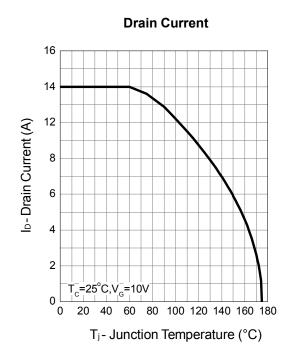
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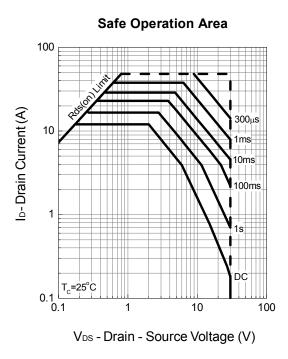


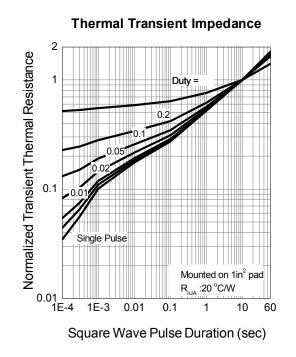
N-Ch and P-Channel MOSFET

N-Channel Typical Characteristics





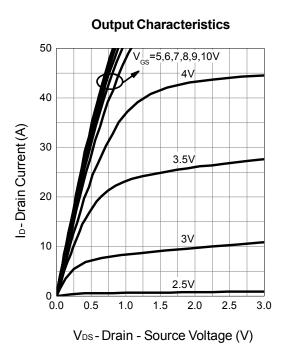


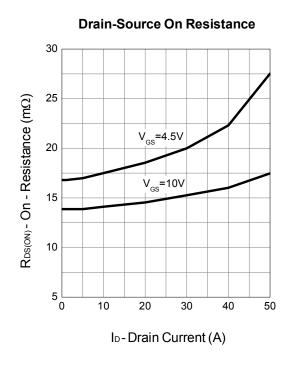


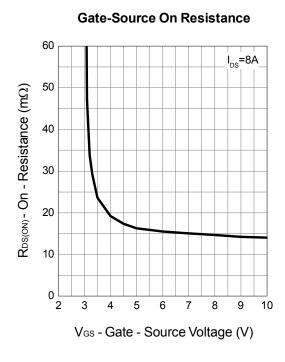


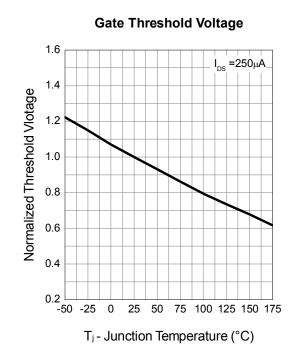
N-Ch and P-Channel MOSFET

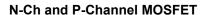
N-Channel Typical Characteristics





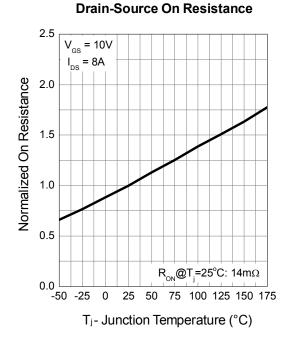




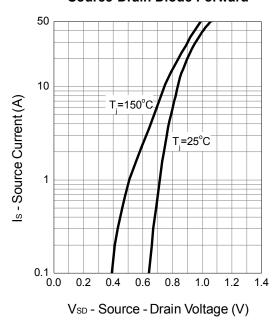




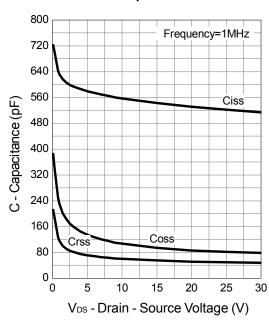
N-Channel Typical Characteristics



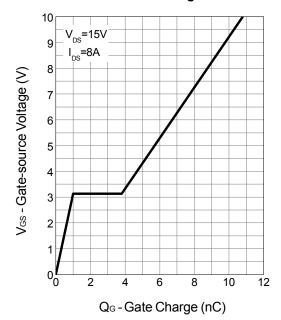
Source-Drain Diode Forward



Capacitance

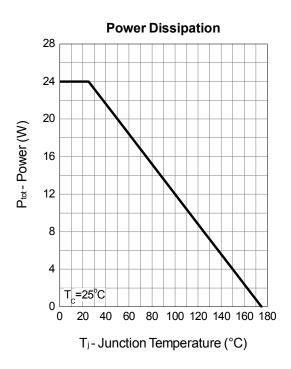


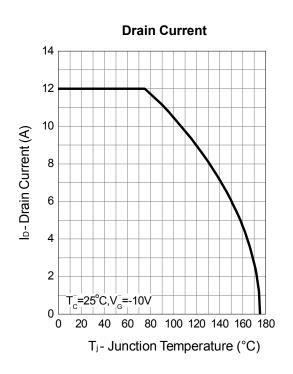
Gate Charge

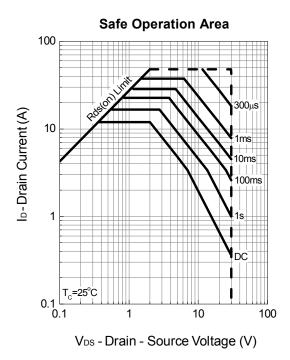


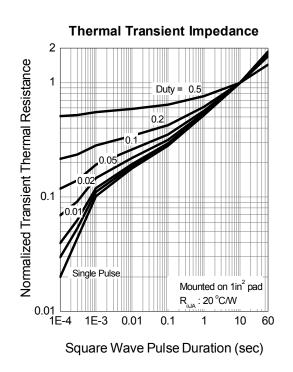


P-Channel Typical Characteristics



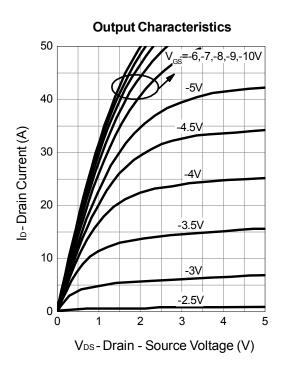


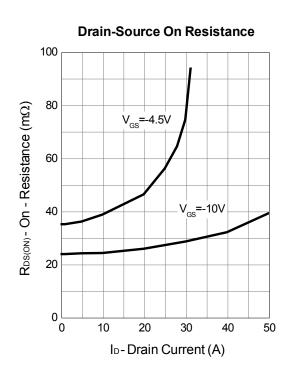


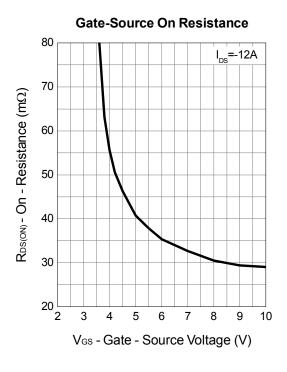


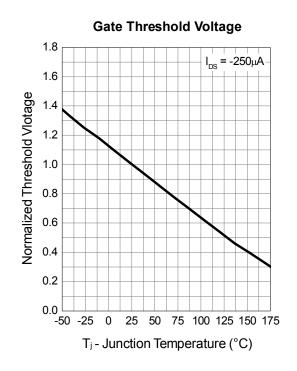


P-Channel Typical Characteristics



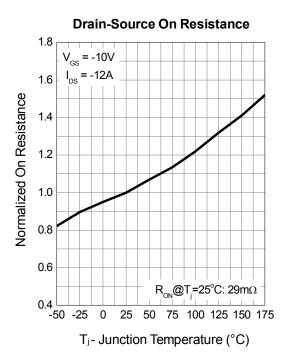


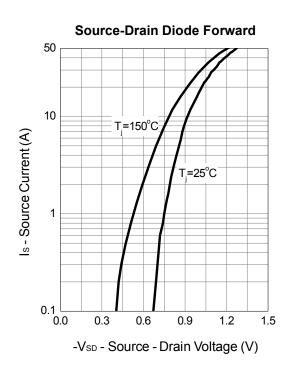


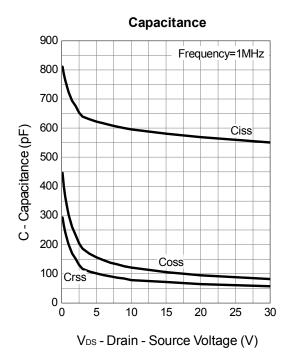


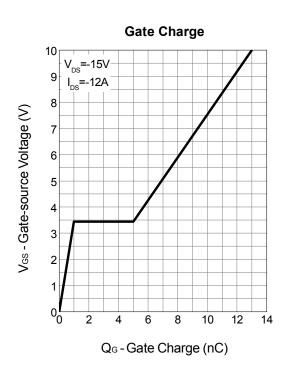


P-Channel Typical Characteristics











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